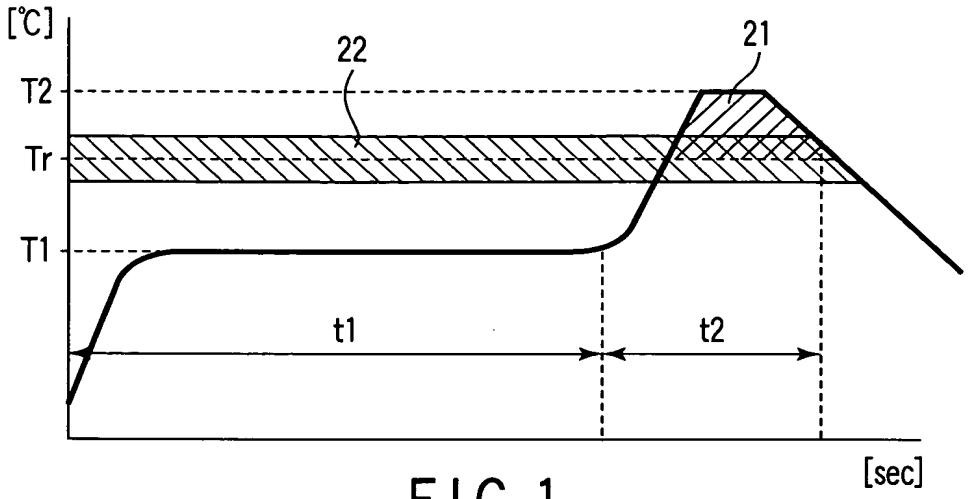



FIG. 1

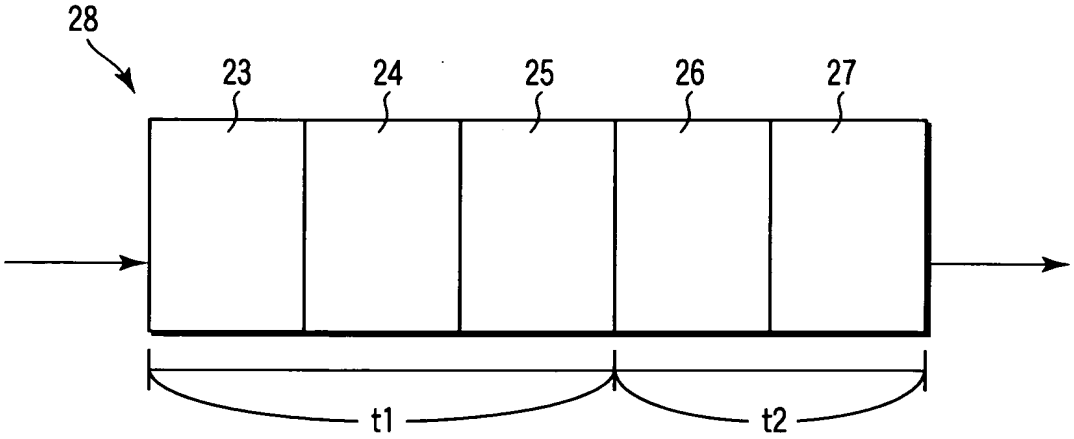



FIG. 2

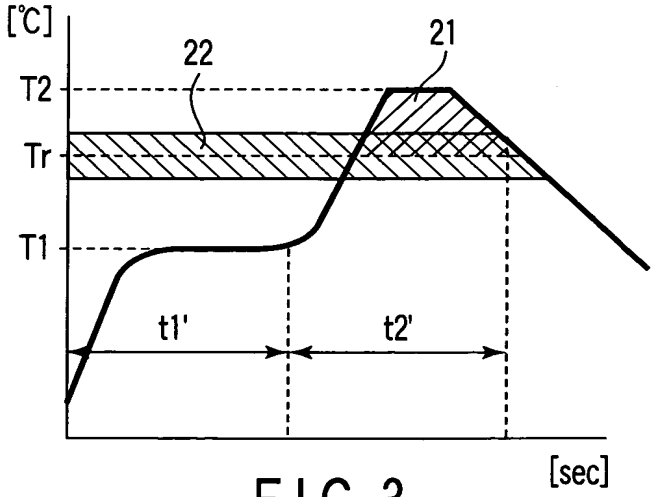



FIG. 3

FIG. 4

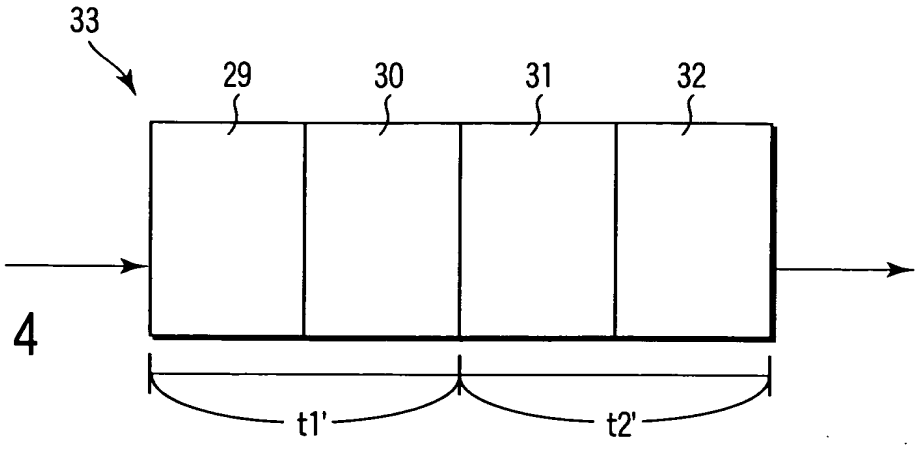



FIG. 5

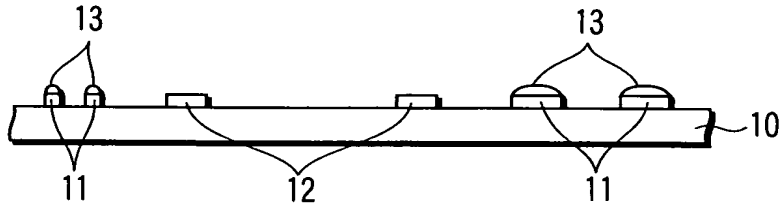



FIG. 6

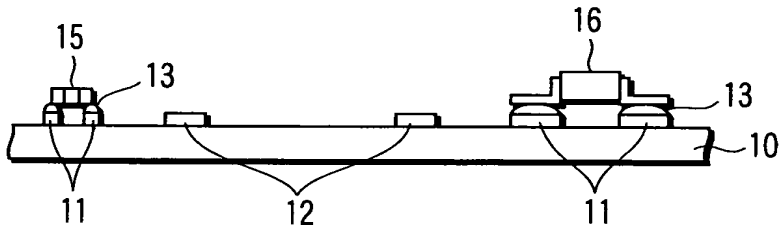



FIG. 7

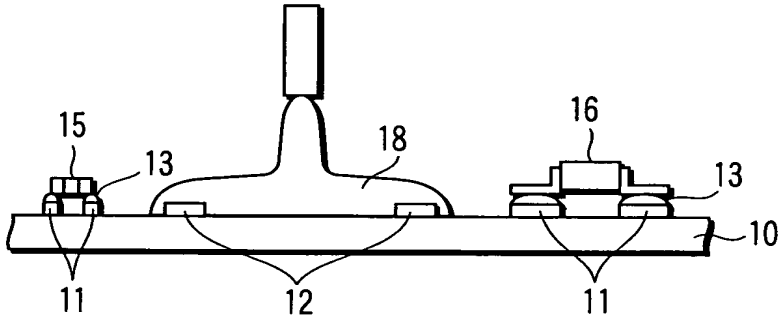
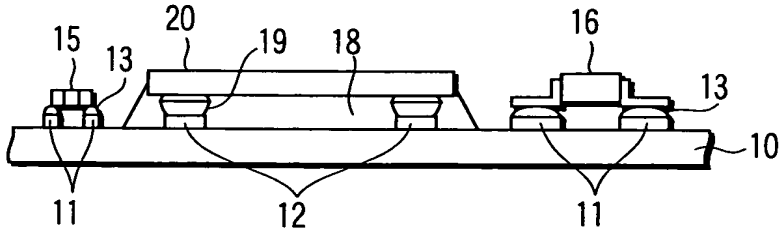



FIG. 8



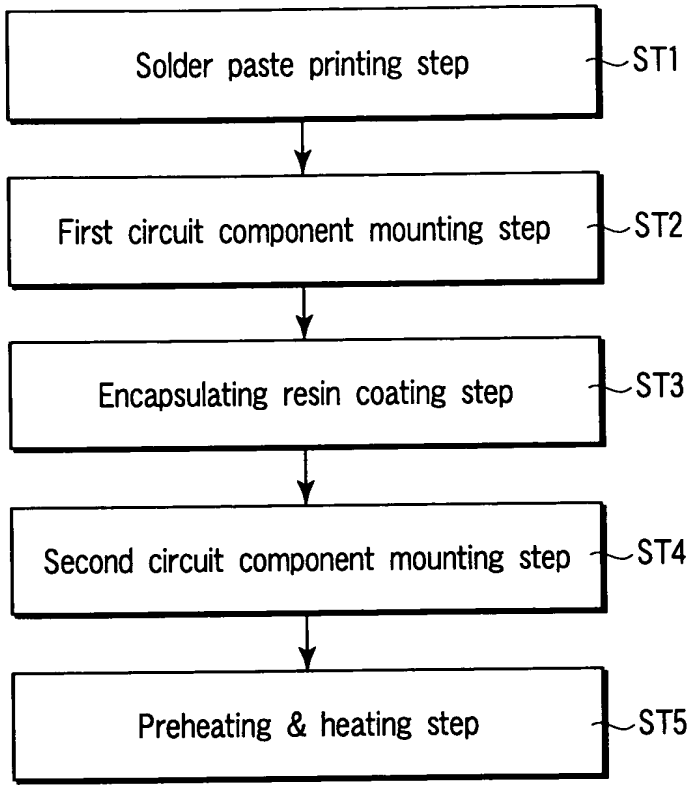

Solder paste printing step
ST1
First circuit component mounting step
ST2
Encapsulating resin coating step
ST3
Second circuit component mounting step
ST4
Preheating & heating step
ST5

FIG. 9

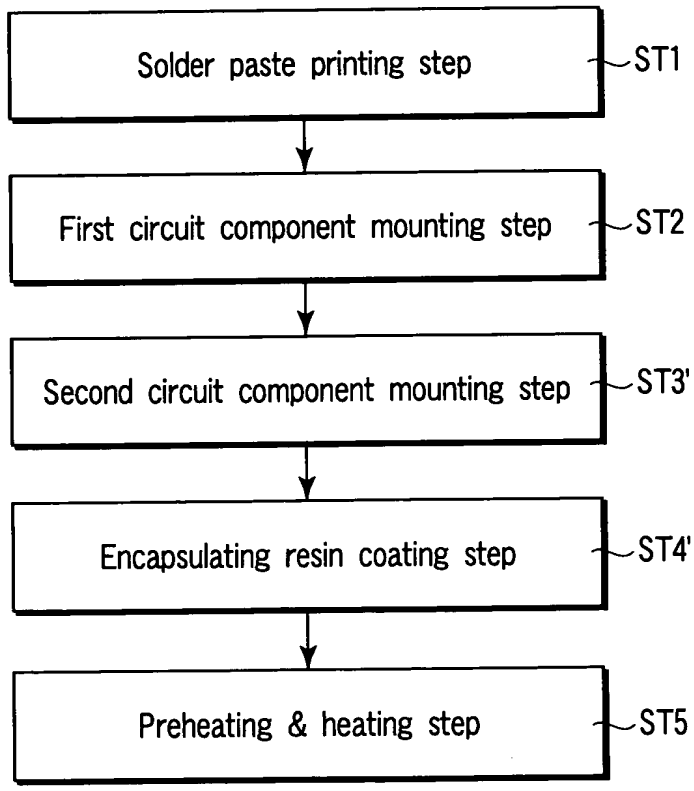

Solder paste printing step
ST1
First circuit component mounting step
ST2
Second circuit component mounting step
ST3'
Encapsulating resin coating step
ST4'
Preheating & heating step
ST5

FIG. 10

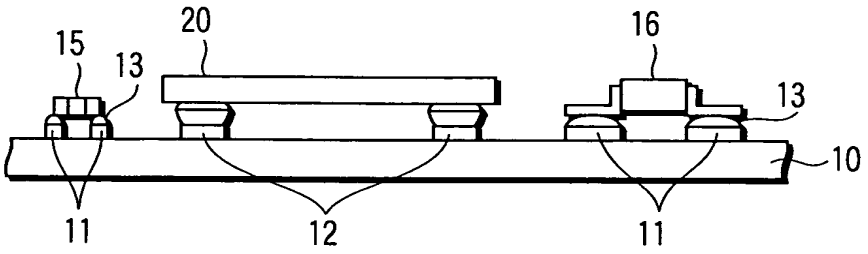



FIG. 11

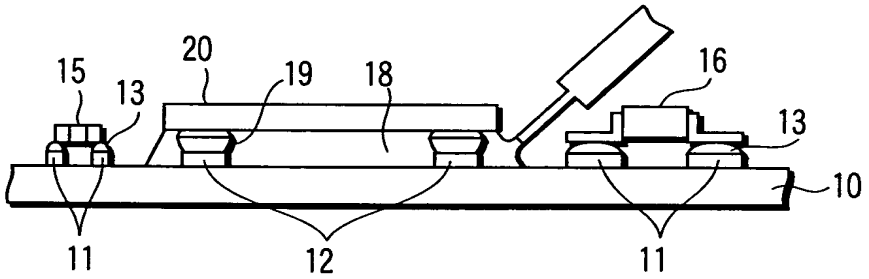



FIG. 12